

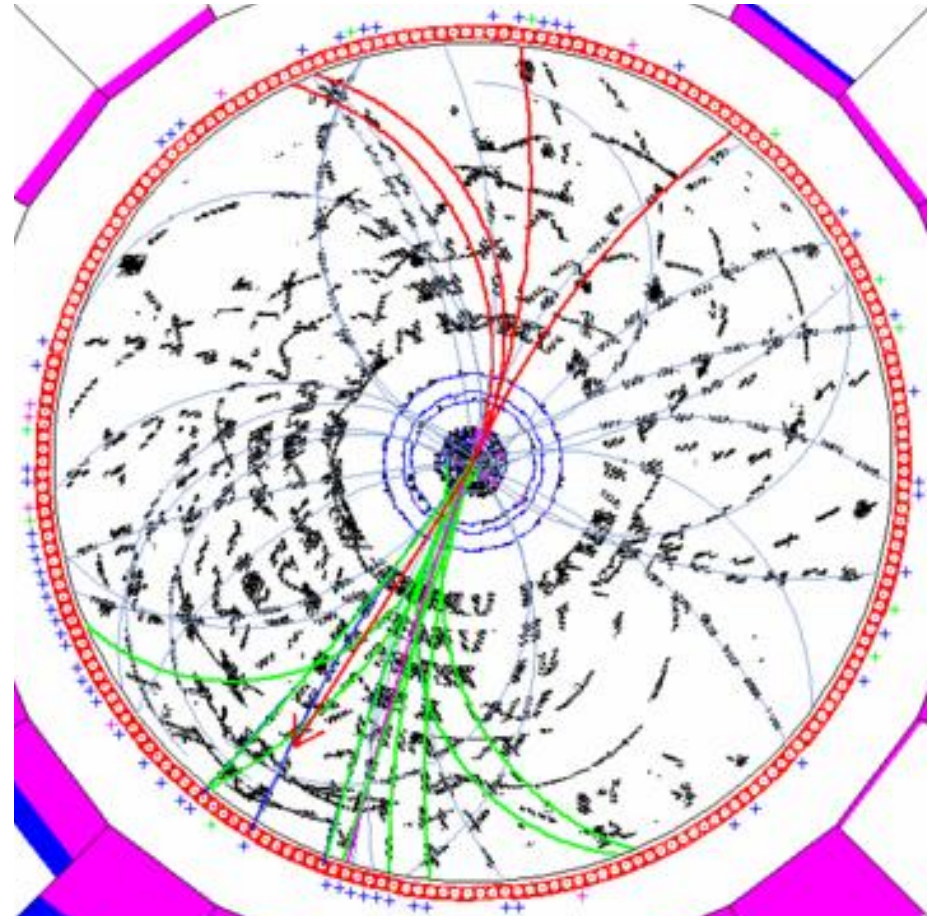
Variable Resolution and ternary cells

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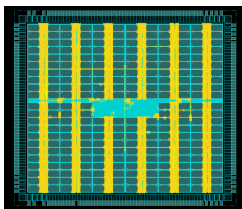
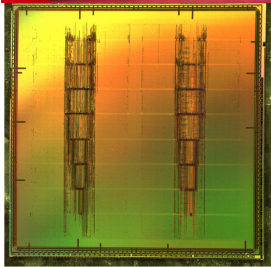
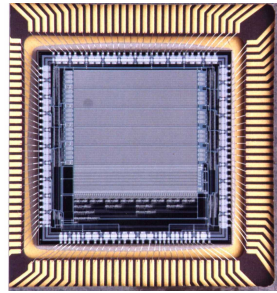
Associative Memories

- First AM for HEP idea
 - M. Dell'Orso, L. Ristori
VLSI Structures for Track Finding
NIM A 278, 436 (1989)
- First application: SVT @ CDF
 - Profit of drift chamber track seed
 - System started with $12 \times 32k$ patterns



We discuss the architecture of a device based on the concept of *associative memory* designed to solve the track finding problem, typical of high energy physics experiments, in a time span of a few microseconds even for very high multiplicity events. This “machine” is implemented as a large array of custom VLSI chips. All the chips are equal and each of them stores a number of “patterns”. All the patterns in all the chips are compared in parallel to the data coming from the detector while the detector is being read out.

AM technological evolution



A. Annovi - March 13th, 2013

- (90's) **Full custom VLSI chip** - $0.7\mu\text{m}$ (INFN-Pisa)
- **128 patterns, 6x12bit words each**

F. Morsani et al., “The AMchip: a **Full-custom** MOS VLSI Associative memory for Pattern Recognition”, IEEE Trans. on Nucl. Sci., vol. 39, pp. 795-797, **(1992)**.

On the opposite side: **FPGA** for the same AMchip

P. Giannetti et al. “A Programmable Associative Memory for Track Finding”, Nucl. Instr. and Meth., vol. A413/2-3, pp. 367-373, **(1998)**.

G Magazzù, 1st standard cell project presented @ LHCC (1999)

Standard Cell $0.18\mu\text{m} \rightarrow 5000$ pattern/Amchip
SVT upgrade total: 6M patterns

L. Sartori, A. Annovi et al., “A VLSI Processor for Fast Track Finding Based on Content Addressable Memories”,

IEEE TNS, Vol 53, Issue 4, Part 2, Aug. **2006**

AMchip04 – 8k patterns in 14mm^2 , 65nm tech.

Power/pattern/MHz ~50 times less. Pattern density x12.

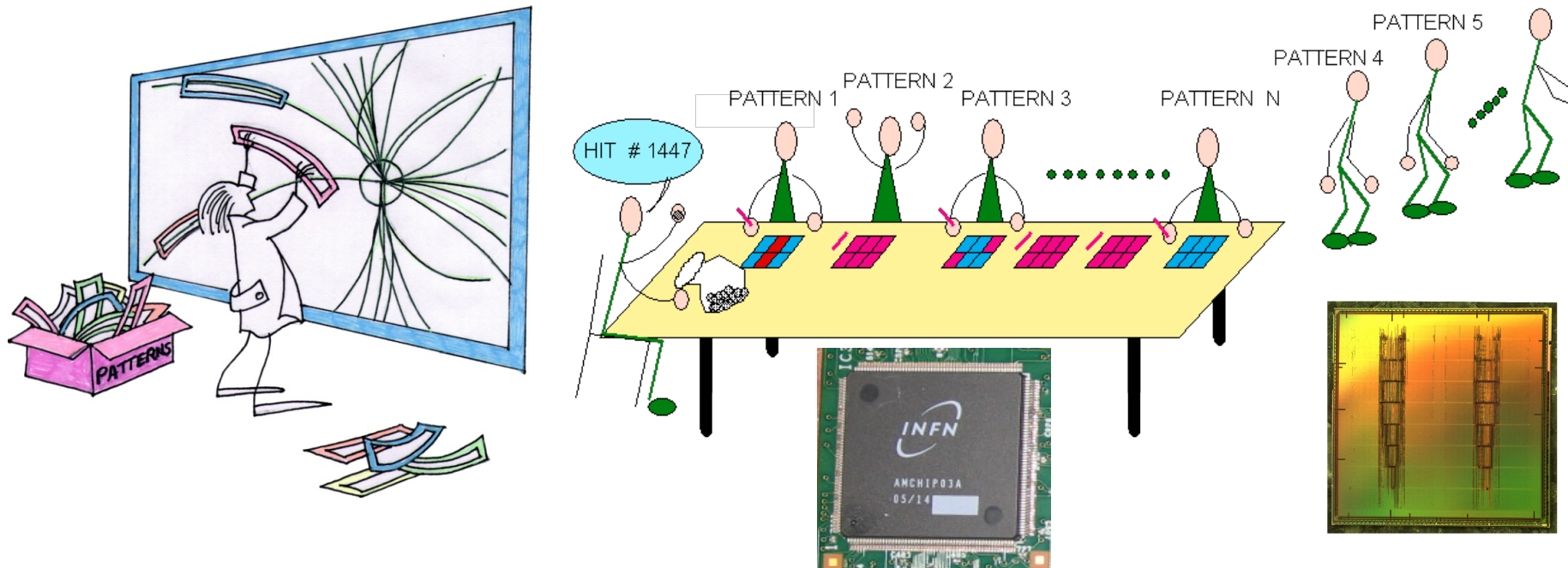
First variable resolution implementation.

F. Alberti *et al* 2013 **JINST** **8 C01040**, doi:[10.1088/1748-0221/8/01/C01040](https://doi.org/10.1088/1748-0221/8/01/C01040)

FTK algorithm:

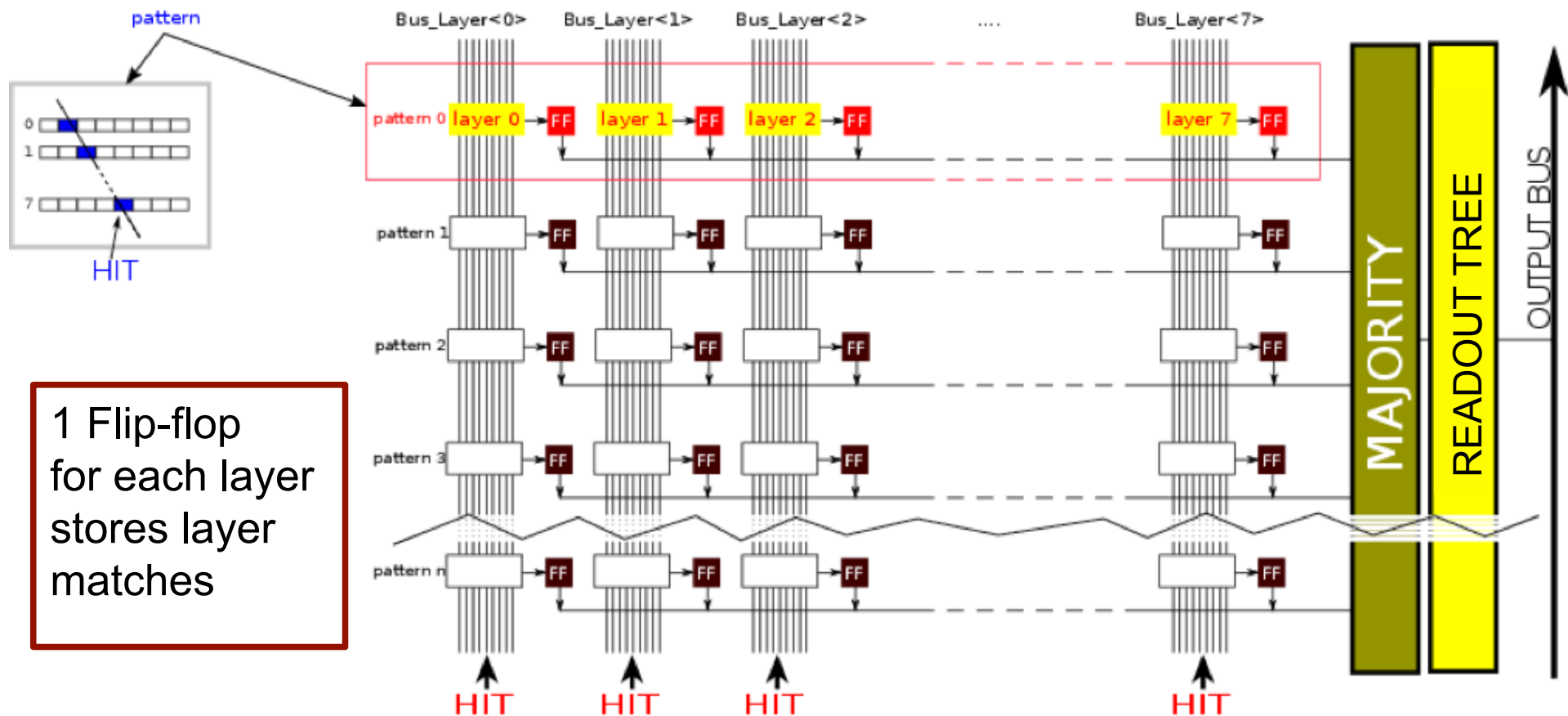
Pattern recognition & Track fitting

- Pattern recognition – find track candidates with enough Si hits



- $O(10^9)$ prestored patterns simultaneously see the silicon hits leaving the detector at full speed.
- Based on the **Associative Memory** chip (content-addressable memory) initially developed for the CDF Silicon Vertex Trigger (**SVT**).

AM working principle



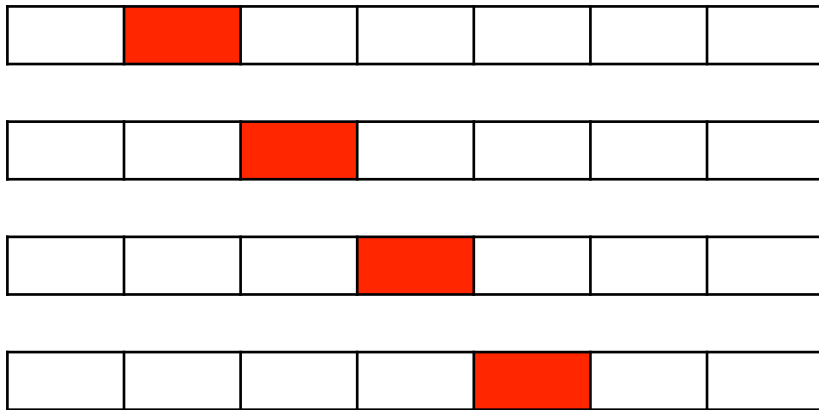
1 Flip-flop
for each layer
stores layer
matches

All patterns compared in parallel with
incoming data. Look for correlation of data
received at different times. (Feature unique
to AMchip)

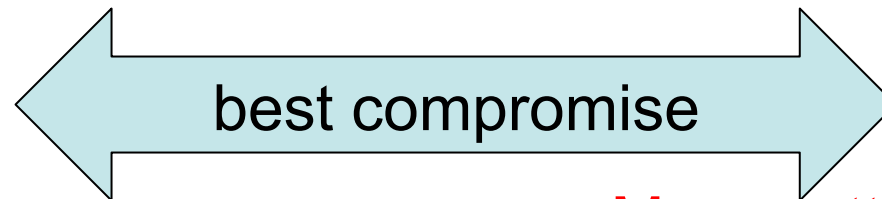
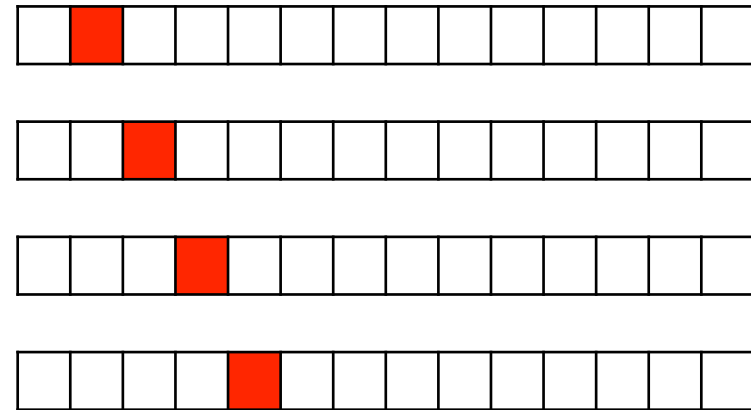
Fast pattern matching.
Flexible input: position,
time, objects...

Generatig the pattern bank

Wide patterns



Thin patterns



High efficiency
with less patterns (hardware)
BUT more fakes

More patterns (hardware)
for same efficiency
less fakes

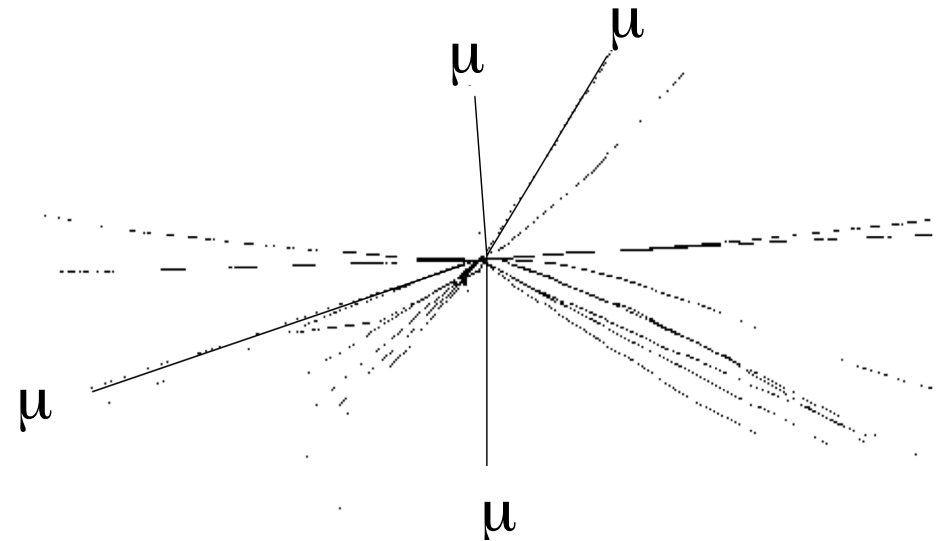
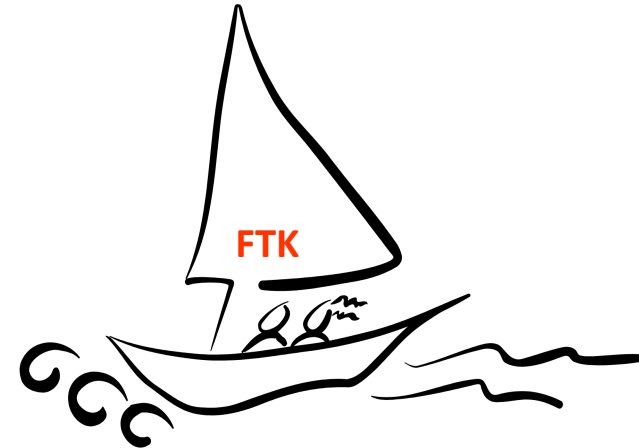
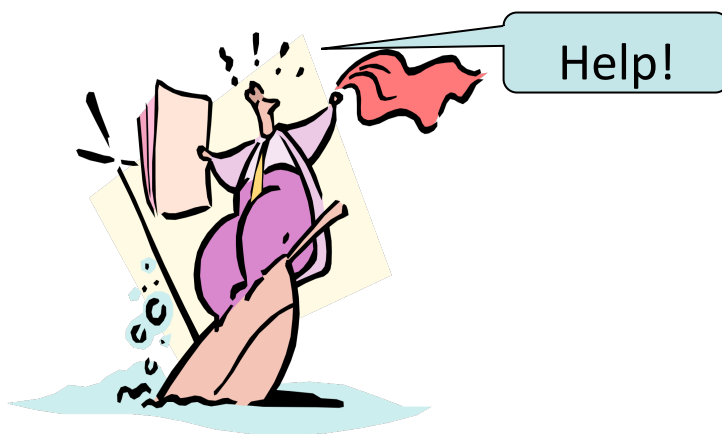
In FTK fakes are workload
for track fitter.

AM at LHC

30 minimum bias events + $H \rightarrow ZZ \rightarrow 4\mu$



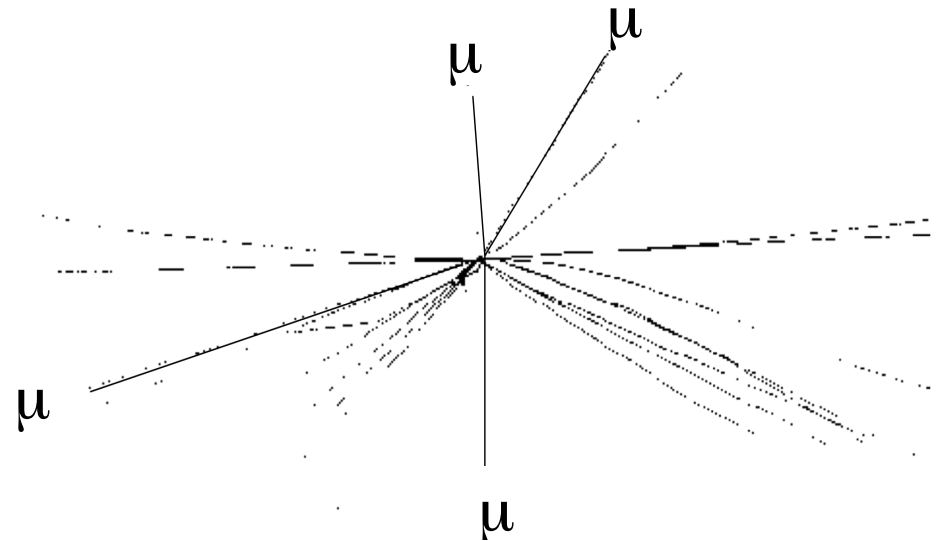
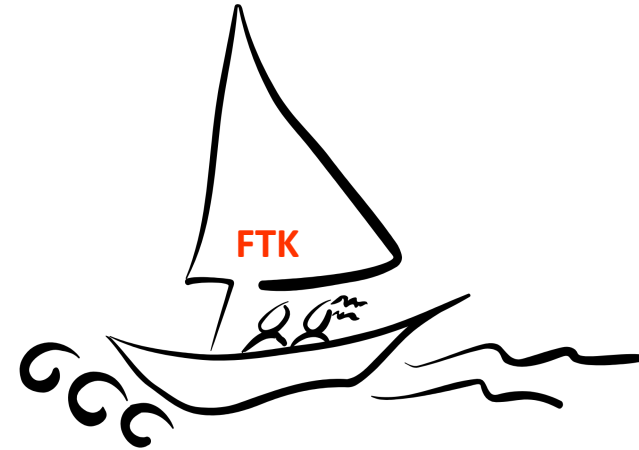
Where is the Higgs?



Tracks with $P_t > 2$ GeV

AM at LHC

- Silicon only tracker
- High luminosity \rightarrow high detector occupancy
- Thousands of tracks / bunch crossing
- For AM to reduce information
 - Need thin AM resolution
 - Need billions of patterns
 - Requires lot's of Amchip...

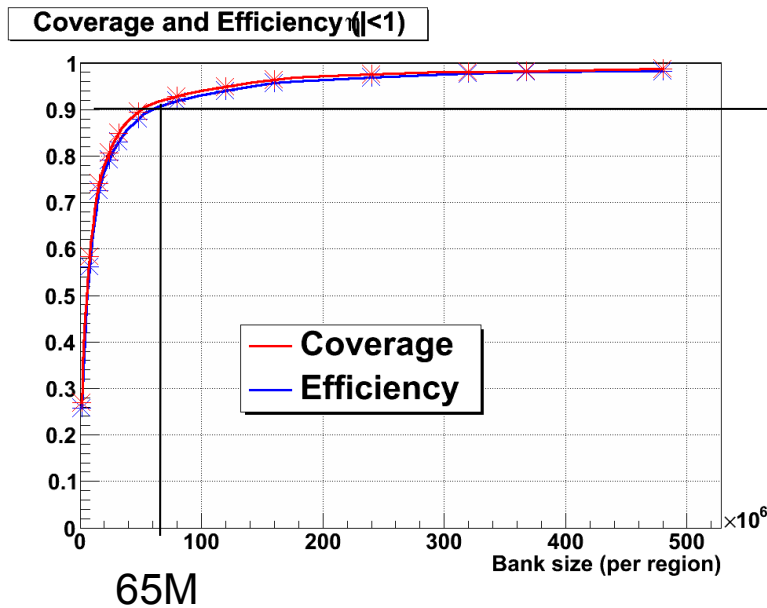


Tracks with $P_t > 2$ GeV

Pattern efficiency

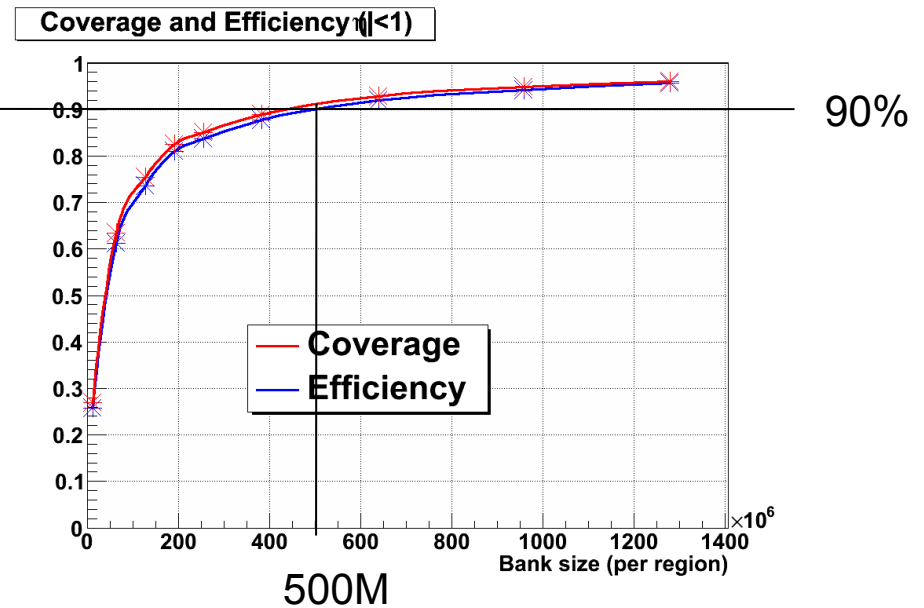
ATL-UPGRADE-PROC-2011-004

Pattern size
r- ϕ : 24 pixels, 20 SCT strips
z: 36 pixels



of patterns in Amchips (barrel only, 45 ϕ degrees)

Pattern size (half size)
r- ϕ : 12 pixels, 10 SCT strips
z: 36 pixels



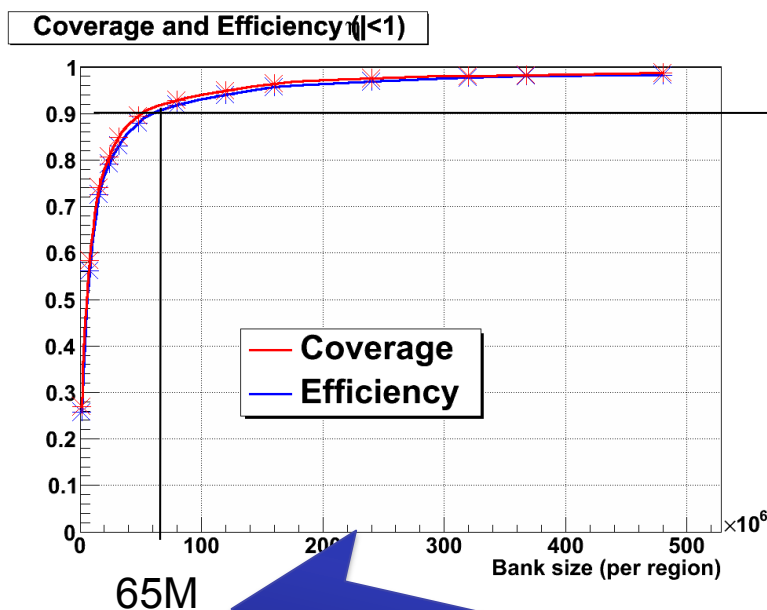
<# matched patterns/event @ 3E34> = 342k

<# matched patterns/event @ 3E34> = 40k

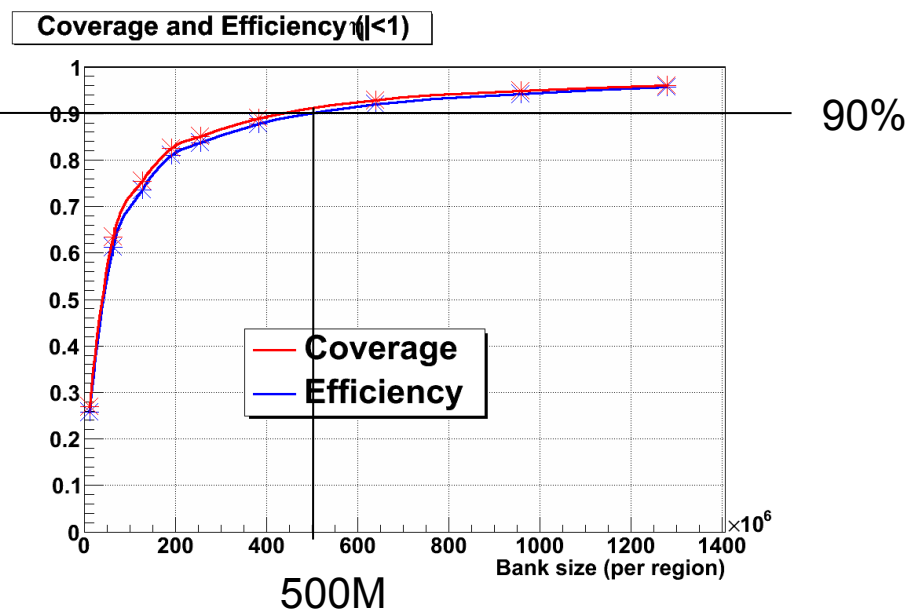
Pattern efficiency

ATL-UPGRADE-PROC-2011-004

Pattern size
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Pattern size (half size)
r- ϕ : 12 pixels, 10 SCT strips
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of (barrel only, 45 ϕ degrees)

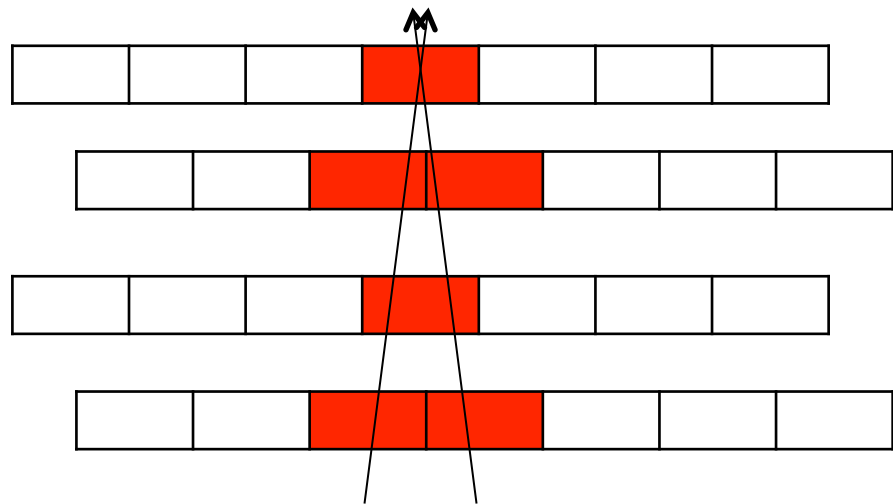
Want this

<# matched patterns/event @ 3E34> = 342k

<# matched patterns/event @ 3E34> = 40k

discretization effects

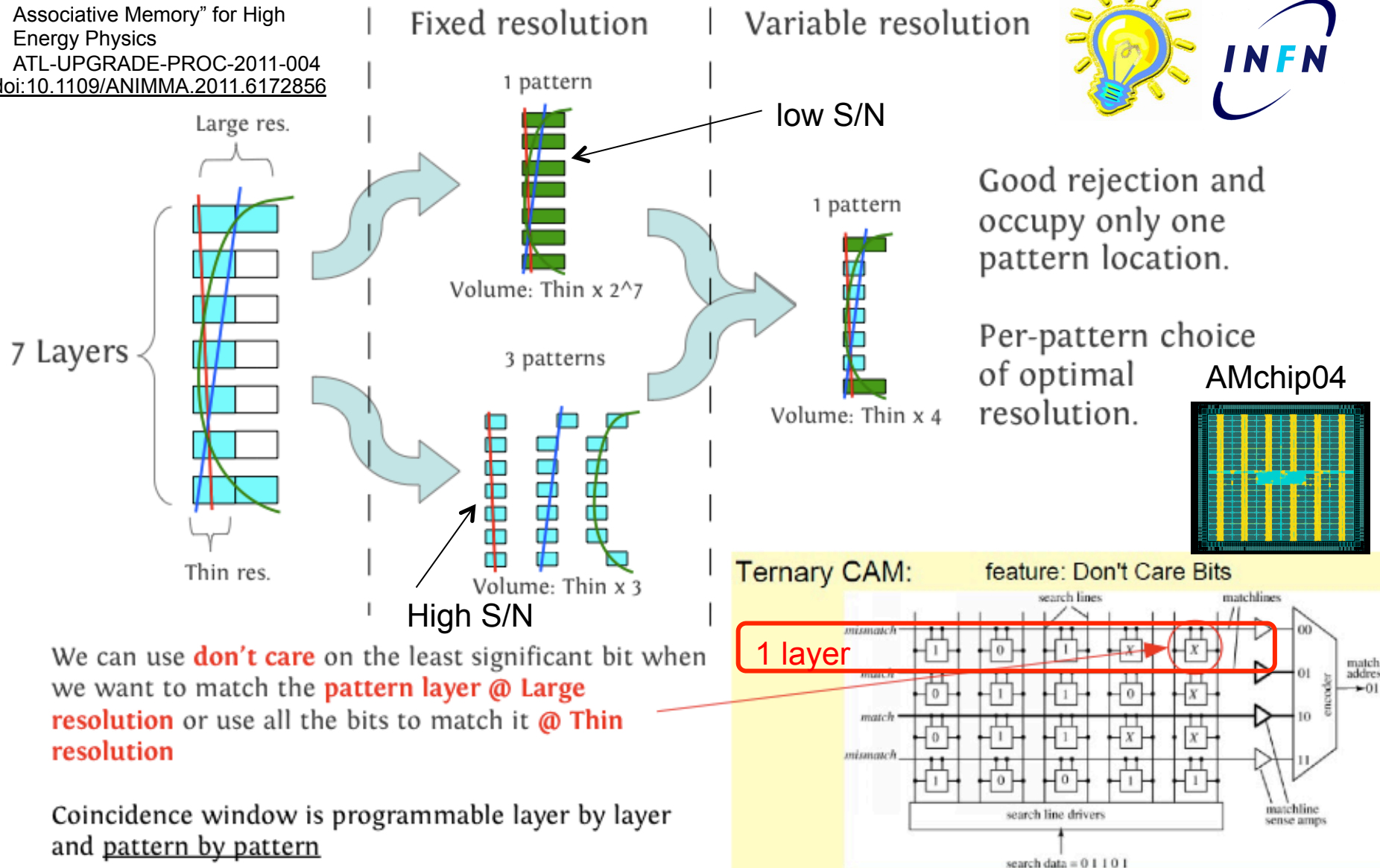
Layers are not aligned



Would use 4
patterns locations
instead of 1 without
variable resolution

AMCHIP04: VARIABLE RESOLUTION

A new "Variable Resolution
Associative Memory" for High
Energy Physics
ATL-UPGRADE-PROC-2011-004
[doi:10.1109/ANIMMA.2011.6172856](https://doi.org/10.1109/ANIMMA.2011.6172856)



We can use **don't care** on the least significant bit when we want to match the **pattern layer @ Large resolution** or use all the bits to match it **@ Thin resolution**

Coincidence window is programmable layer by layer and pattern by pattern

The patterns: a different point of view

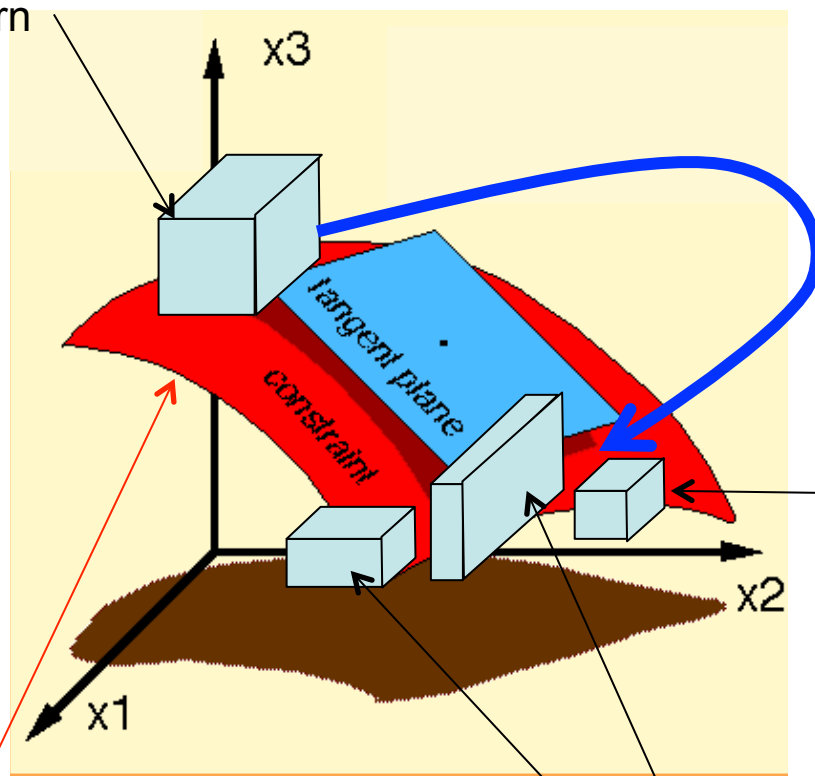
5 strip + 3 pixel layers
→ 11 coordinates
→ 11D hit coord. space

A factor of 2 on each side
→ a factor 2^{11} less volume
→ $O(1/2048)$ less fakes!!
... forgetting correlated hits

The pattern bank:

- cover the track manifold with patterns.
- covered space outside manifold → fakes.
- variable resolution → dramatically improves S/N

Large pattern



Thin pattern

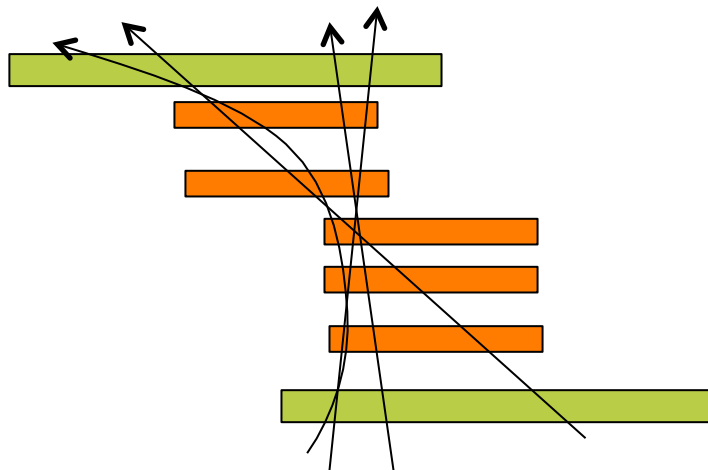
Fixes resolution
patterns → fixed
aspect ratio

5D track manifold

Variable resolution patterns



Many bits variable resolution

1 bit variable resolution

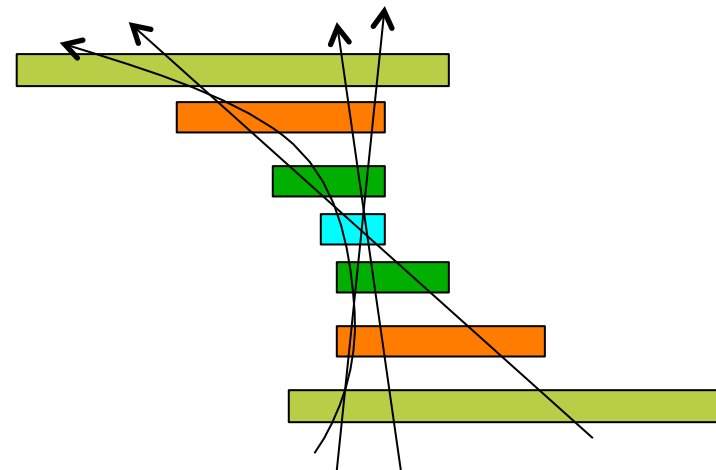


1 pattern

Volume 4^* 

Volume $2^{(7*2)*4^*}$  = 2^{16} 

3 bit variable resolution



1 pattern

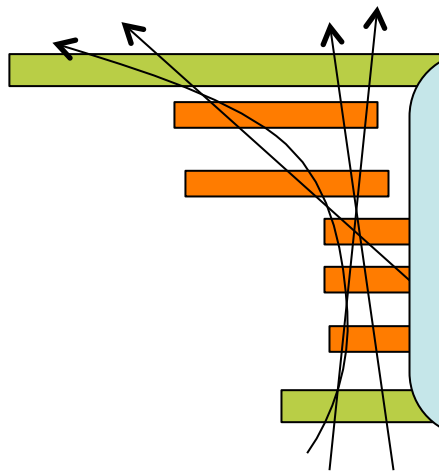
Volume $1/4^*$ 

Volume 2^{12} 

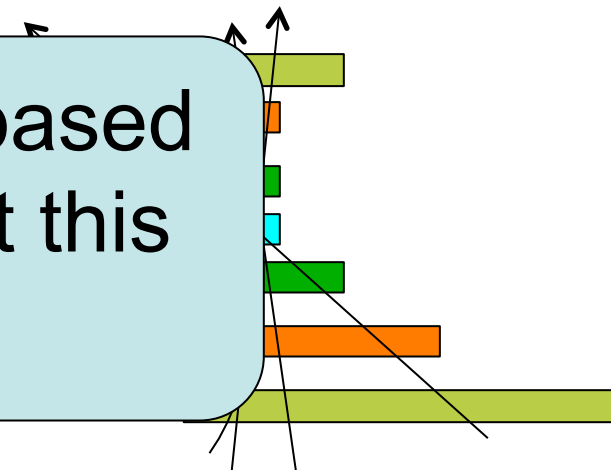
1/16 less volume
less fakes!!!

Many bits variable resolution

1 bit variable resolution





3 bit variable resolution



Any coincidence based trigger can exploit this technique!!!!

1 pattern

Volume 4^* 

Volume $2^{(7*2)*4^*}$  = 2^{16} 

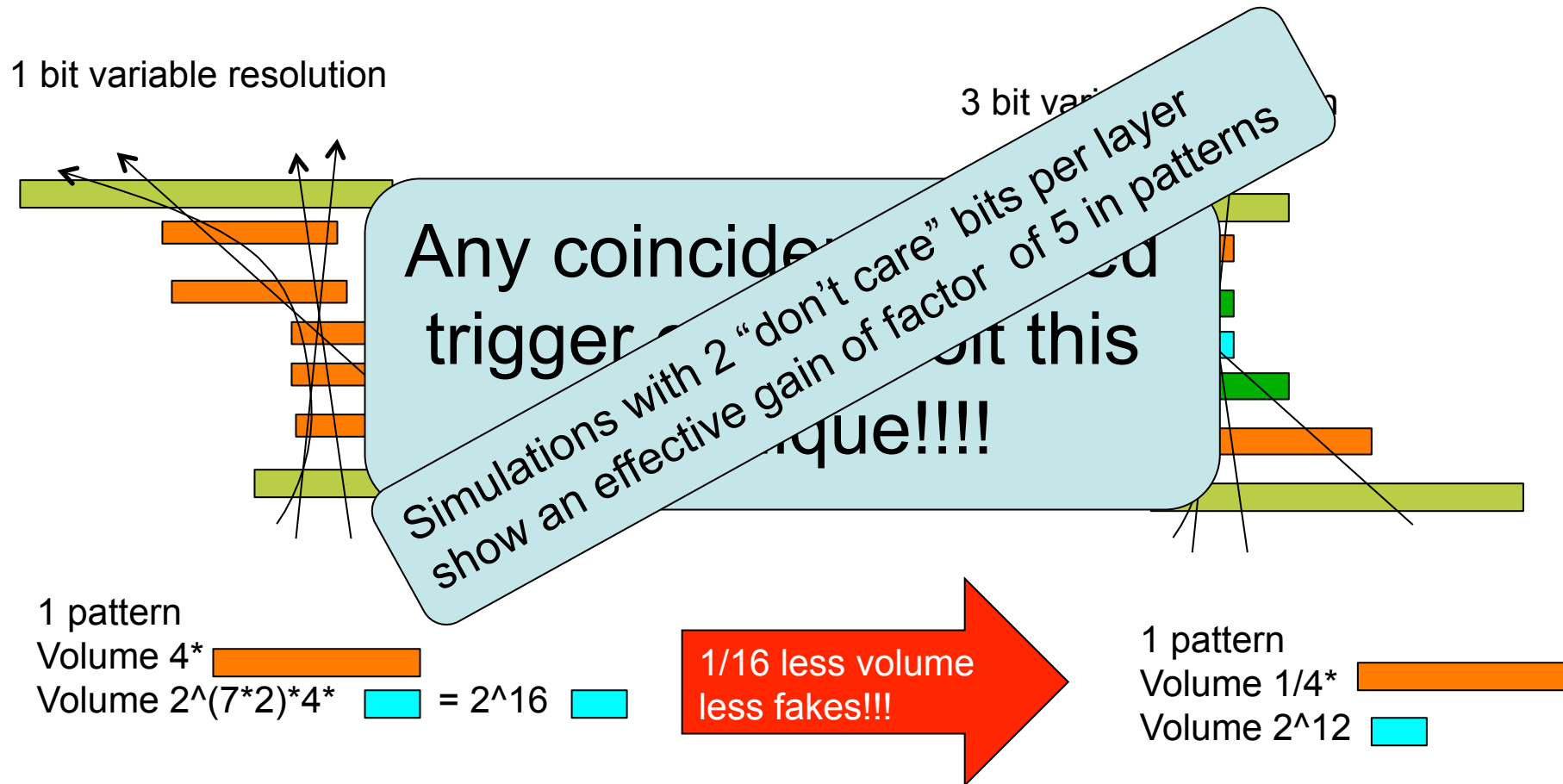
1/16 less volume
less fakes!!!

1 pattern

Volume $1/4^*$ 

Volume 2^{12} 

Many bits variable resolution



Ternary CAM Cell with two NOR type cells

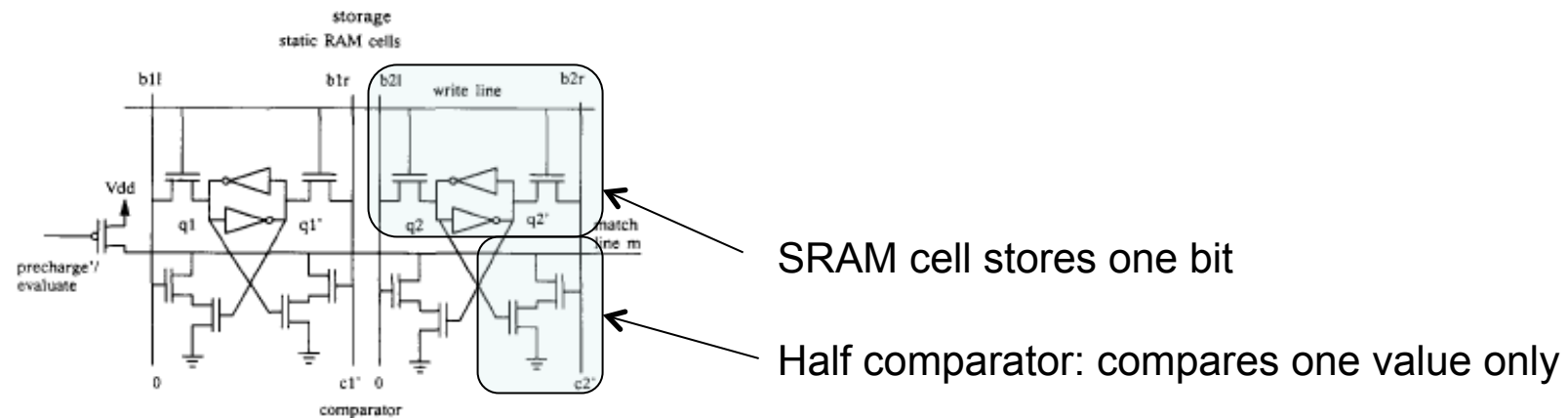


Fig. 8. Two adjacent static binary CAM cells.

Images from: "Encoding Don't Cares in Static and Dynamic Content-Addressable Memories", Sergio R. Ramirez-Chavez, IEEE Transactions on circuits and system-II: Analog and Digital Signal Processing, Vol. 39 NO. 8, August 1992

Ternary CAM Cell with two NOR type cells

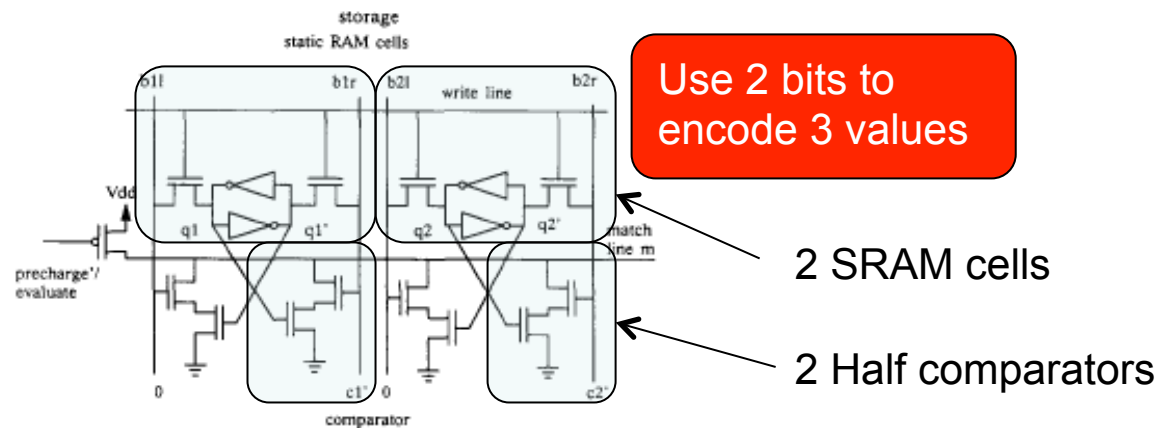


Fig. 8. Two adjacent static binary CAM cells.

Can use from 3 to 6 ternary cells per layer.
Variable resolution 1-8 up to 1-64.

Images from: "Encoding Don't Cares in Static and Dynamic Content-Addressable Memories", Sergio R. Ramirez-Chavez, IEEE Transactions on circuits and system-II: Analog and Digital Signal Processing, Vol. 39 NO. 8, August 1992

Ternary CAM Cell with two NOR type cells

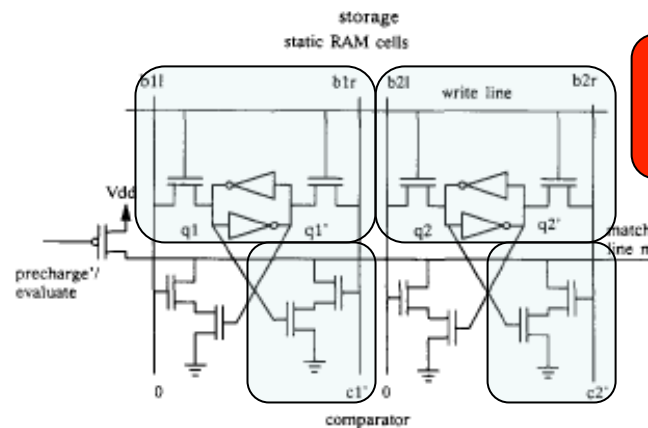


Fig. 8. Two adjacent static binary CAM cells.

Use 2 bits to encode 3 values

storage scheme
stored values

q1q2

0 01
1 10
* 00

(a)

retrieval scheme
presented values

presented
ternary
value

encoded value in
the bit lines of two
binary static CAMs.

binary CAM
equivalent
operation

	c1c2	b1l	b1r	b2l	b2r	l r
0	01	0	1	0	0	0 M*
1	10	0	0	0	1	M 0
*	11	0	0	0	0	M M

*M is the masking of a bit operation common in commercial binary CAMs.

(b)

Each cell does
half comparison

Can use from 3 to 6 ternary cells per layer.
Variable resolution 1-8 up to 1-64.

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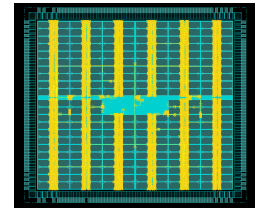
Fig. 9. Encoding and retrieval schemes for don't-care in two static binary CAM's cells with masking capability. (a) Encoding scheme. (b) Retrieval scheme.

Two bitlines always set to 0

CAM cell configuration

- 18 CAM bits per layer: 4 NAND and 14 NOR
 - NOR pairs can make a ternary cell
- Default 12 bits + 3 ternary (minimum)
 - 15 bits per input bus (maximum)
 - (14:7) NOR, (6:3) 4 NAND, (2:0) 3 NOR-pairs
- 6 bits + 6 ternary (maximum)
 - Use only 12 bits per input bus
 - (11:10) NOR, (9:6) 4 NAND, (5:0) 6 NOR-pairs
- Ternary cells (NOR pairs) mapped to LSBs
- NAND cells are mapped to LSBs after the ternary cells, when they don't match small power consump.

AMchip04



Input buses
15 bits each

Summary

- Introduced an innovative AM algorithm
 - Resolution variable layer-by-layer and pattern-by-pattern
- Equivalent to a factor 3-5 extra patterns or more
 - Not fully exploited yet
- Any coincidence based trigger can profit